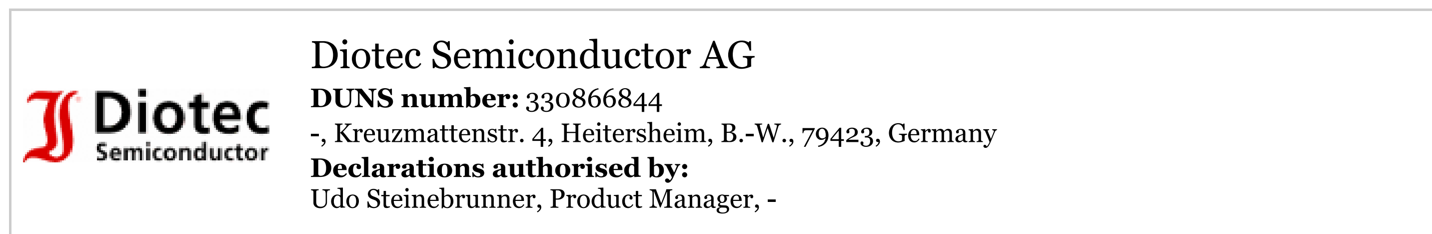
BOMcheck.net

Full Material Declaration for attached parts list

Report generated: 11 March 2016, 10:02 GMT



Diotec Semiconductor AG
DUNS number: 330866844
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Declarations authorised by:
Udo Steinebrunner, Product Manager, -

Declaration effective from: 1 May 2009 [Approved on 11 March 2016, 10:04 GMT]

Materials and substances

Use/Location	Material group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.50000%	Gold	7440-57-5	8.50000%
			ALUMINIUM	7429-90-5	12.00000%
			Silicon	7440-21-3	79.50000%
Die attach	Gold plating	0.12000%	Tin	7440-31-5	20.00000%
			Gold	7440-57-5	80.00000%
Encapsulation	EP (Epoxy resin)	52.10000%	Carbon black	1333-86-4	0.30000%
			ANTIMONY TRIOXIDE	1309-64-4	0.80000%
			2,2-Bis(4(2',3'-epoxypropoxy)phenyl)propane	1675-54-3	0.99000%
			Epoxy resin 89	26335-32-0	27.61000%
			Quartz sand	60676-86-0	70.30000%
Inner preparation	Gold	0.04500%	Gold	7440-57-5	100.00000%
Leadfinish	Tin plating	0.90000%	Tin	7440-31-5	100.00000%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	46.33500%	Silver	7440-22-4	0.48000%
			Copper	7440-50-8	0.95000%
			Iron	7439-89-6	98.57000%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
TO-92	TO-92	0.18	g